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Design for package, design for test

Thomas G. Brown
University of Rochester
thomas.brown@rochester.edu

Abstract – Two of the significant cost barriers for high volume, high speed silicon photonics are high throughput testing and optical connections that facilitate both testing and final packaging. This paper will review the options available for optical I/O, present some of the current manufacturing solutions, and describe efforts both around the world and within AIM Photonics that aim to meet these challenges.

Bio – Thomas Brown has been serving on the faculty of the Institute of Optics, University of Rochester since 1987. He is a Fellow of the Optical Society of America, is former President and honorary member of the Rochester Local Chapter of the Optical Society of America, and has served as Chair of the Polarization Engineering technical group of the OSA. He was the founding director of the Robert E. Hopkins Center for Optical Design and Engineering, and co-chairs the annual conference on multidimensional microscopy at Photonics West. He currently serves as academic co-lead for the Test, Assembly and Packaging program within AIM Photonics. His research specialties are in the areas of polarized light, optical metrology and nano-photonics.